



## RMAI DIVERSITY EQUITY INCLUSION Belonging (DEIB) 2025 ANNUAL CONFERENCE SCHOLARSHIP

RMAI's Annual Conference, one of the receivables management industry's most respected and well-attended events each year, presents high-quality educational programs and networking activities. The conference allows attendees to engage with industry leaders on topics designed to promote, support, and drive uniform industry best practices as well as our national Receivables Management Certification Program standards. Equally important is the time together to strengthen connections and create opportunities to grow new business for thriving in an ever-changing environment.

RMAI is an inclusive organization that fosters the participation of a diverse group of employees from all member companies in all RMAI networking activities, educational programming, and committee service. To that end, RMAI created the **DEIB Annual Conference Scholarship** to provide qualified employees of RMAI member companies either a partial or full scholarship to the Annual Conference covering registration, travel, and hotel costs associated with conference attendance. The 2025 Annual Conference will be held at the Aria Resort & Casino in Las Vegas, Nevada, February 10-13. [Learn more.](#)

Scholarship recipients will not only attend the conference but will participate in organized networking opportunities designed to provide lasting mentorship and career guidance.

### Who Should Apply?

The scholarship is open to all receivables management professionals employed by an RMAI member company who have never attended an in-person RMAI event (i.e., Annual Conference, Executive Summit, or regional event) and are viewed as emerging leaders in their organization. The scholarship is committed to promoting leadership development and diversity within our membership and the industry. We are actively seeking applications from Black, Latinx, and Native American employees as well as from members of the LGBTQ community, veterans, and individuals with disabilities.

### How to Apply

Qualified employees of member companies should send the following items to [info@rmaintl.org](mailto:info@rmaintl.org)

- The 2025 RMAI DEIB Scholarship Application
- A letter of interest explaining the applicant's qualifications, why the applicant would like to attend the conference, and what the applicant hopes to learn/achieve from attendance.
- Resume
- The 2025 RMAI DEIB Scholarship Manager's Form
- A letter of recommendation from manager identifying the applicant as an emerging business leader\* and addressing the applicant's leadership strengths. (Note: This letter of recommendation should be specific for the applicant and include examples.)

Applications must be submitted on or before October 15, 2024. Scholarship recipients must be willing to:

- Attend and fully participate in the 2025 RMAI Annual Conference, including education sessions, networking events, exhibit hall hours, the pre-conference First Time Attendee Zoom meeting, and the First Time Attendee Lunch at the conference
- Write a recap of approximately 500 words about their experience as a first time Annual Conference attendee. This article should cover the value they found in attending the Annual Conference and discuss what they see as the future of the receivables management industry. In addition to the Annual Conference experience, this is an opportunity to have an article published by RMAI and promoted to the industry

\*An emerging business leader is someone whom management has identified as a good candidate for the role because of leadership skills seen on the job and explained in a thoughtful letter of recommendation from the applicant's manager. These skills include communication, motivation, delegation, positivity, trustworthiness, creativity, feedback, responsibility.

## How to Sponsor

Interested in sponsoring the RMAI DEIB Annual Conference Scholarship or other sponsorship opportunities? Reach out to Event & Sales Development Manager, Sylvia Done at [sdone@rmaintl.org](mailto:sdone@rmaintl.org) or 916-779-2497.

The DEIB Scholarship Sponsorship is available to RMAI members only (\$4,000 each) with the following benefits:

- 2025 RMAI Annual Conference Attendee listings (3 pre-event, 1 post-event), including contact information
- Logo on the 2025 RMAI Annual Conference on-site entranceway
- Recognition at 2025 RMAI Annual Conference General Session
- Recognition on the 2025 Annual Conference sponsor webpage
- Listing on 2025 RMAI Annual Conference pocket guide sponsor page
- Listing on 2025 RMAI Annual Conference program book sponsor page

## RMAI's DEIB Committee

The RMAI DEIB Task Force, upon creation in February 2019, identified a vision, mission, set of values, and task force goals. In February 2023, the RMAI Board of Directors made the task force a standing committee in recognition of the commitment to its vision to create opportunities for RMAI members to recognize, embrace, and leverage diversity in their workforce, including all people to enhance every aspect of their businesses and the industry. The DEIB Committee works to accomplish its mission to empower RMAI member companies to create an inclusive culture by delivering rich content and experiences on diversity, equity and inclusion practices that will allow their businesses to thrive, and by upholding values that promote representation by unique contributors, respect and embrace all ideas, cultivate a safe environment where all are encouraged to participate, and inspire and lead change. The DEIB Committee is also the selection committee for DEIB Scholarships.



## Diversity Equity Inclusion Belonging (DEIB) Scholarship Application 2025 RMAI Annual Conference Attendance

RMAI created the DEI Annual Conference Scholarship to promote leadership development and diversity within RMAI membership and the receivables management industry.

Applicant Name: \_\_\_\_\_ Company Name: \_\_\_\_\_

Title: \_\_\_\_\_ Years at Current Company: \_\_\_\_\_ Years in the Industry: \_\_\_\_\_

Business Address: \_\_\_\_\_

City: \_\_\_\_\_ State: \_\_\_\_\_ Zip: \_\_\_\_\_

Cell Phone: \_\_\_\_\_ Email: \_\_\_\_\_

Please indicate why you believe you qualify for this scholarship by checking all applicable boxes below.

- |  |   |
|--|---|
| <input type="checkbox"/> Black           | <input type="checkbox"/> Veteran                  |
| <input type="checkbox"/> Latinx          | <input type="checkbox"/> Person with a Disability |
| <input type="checkbox"/> Native American | <input type="checkbox"/> Other                    |
| <input type="checkbox"/> LGBTQ           |   |

Please confirm the following by checking the boxes below.

I am a first-time attendee of an in-person RMAI event (i.e. RMAI's Annual Conference, Executive Summit or regional event).

My letter of interest explains why I believe I qualify for this scholarship, why I would like to attend the Conference, and what I hope to learn/achieve from my attendance.

If selected for this scholarship, I commit to attending and fully participating in the 2025 RMAI Annual Conference, including education sessions, networking events, exhibit hall hours, the First Time Attendee Zoom meeting prior to the Conference, and the First Time Attendee luncheon at the Conference.

If selected for this scholarship, I commit to writing a 500-word recap about my experience at the conference, the value I found in attending and what I see as the future of the receivables management industry, which may be featured in a publication by RMAI.

Signature: \_\_\_\_\_ Date: \_\_\_\_\_



## Diversity Equity Inclusion Belonging (DEIB) Scholarship Application - Manager's Form 2025 RMAI Annual Conference Attendance

RMAI created the DEIB Annual Conference Scholarship to promote leadership development and diversity within RMAI membership and the receivables management industry.

Manager Name: \_\_\_\_\_ Company Name: \_\_\_\_\_

Title: \_\_\_\_\_

Business Address: \_\_\_\_\_

City: \_\_\_\_\_ State: \_\_\_\_\_ Zip: \_\_\_\_\_

Cell Phone: \_\_\_\_\_ Email: \_\_\_\_\_

Applicant Name: \_\_\_\_\_ Years at Company: \_\_\_\_\_

Please confirm the following by checking the boxes below. To be eligible, applicants must work for an RMAI Member company and be able to attend Annual Conference.

If selected for this scholarship, this applicant is able to attend the 2025 RMAI Annual Conference, the First Time Attendee Zoom meeting prior to the Conference, and the First Time Attendee luncheon at the Conference.

My letter of recommendation identifies the applicant as an emerging leader and addresses the applicant's strengths in the following leadership skills, which I have also rated (1 to 5, 5 as highest) below:

- \_\_\_\_\_ **Communication:** Able to present information in a clear and articulate manner that facilitates collaboration.
- \_\_\_\_\_ **Motivation:** Shows independent drive to succeed at personal and company goals.
- \_\_\_\_\_ **Delegation:** Gives others appropriate opportunities to act; makes intelligent choices on assignments; works to grow the abilities of others.
- \_\_\_\_\_ **Positivity:** Maintains a mindset of confidence focused on opportunity; contributes to a supportive and affirming culture.
- \_\_\_\_\_ **Trustworthiness:** Honest and communicative; admits to any mistakes and seeks to resolve any issues.

*Continued on next page*

\_\_\_\_\_ **Creativity:** Demonstrates innovation and imagination in the execution of projects and the presentation of new ideas.

\_\_\_\_\_ **Feedback:** Provides valuable information and analysis on others' work; gives appropriate recognition and appreciation where due; is receptive to receiving comments and input.

\_\_\_\_\_ **Responsibility:** Commits to accountability; takes ownership of work.

*Note:* Please take the time to make your letter of recommendation specific to your applicant by including distinctive examples of the applicant's strengths. If recommending more than one applicant, avoid copying and pasting the same wording.

Signature: \_\_\_\_\_ Date:

*Please return this form and your letter of recommendation to the applicant for submission to [info@rmaintl.org](mailto:info@rmaintl.org). Applications are due October 15, 2024.*